

SPECIFICATION

MODEL: BH-LV02-A01

Rev: 1.1

Part Number:

Published Date:

Approved by		
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REVISION HISTORY

Rev	DATE	PAGE	DESCRIPTION	AUTHOR
1.0	17.08.28	All	First issued	
1.1	19.05.09	2,4,5	Update Board Picture; Modify LVDS OUT definition 更换板卡示意图, 用卧式插针, 修正输出LVDS定义	

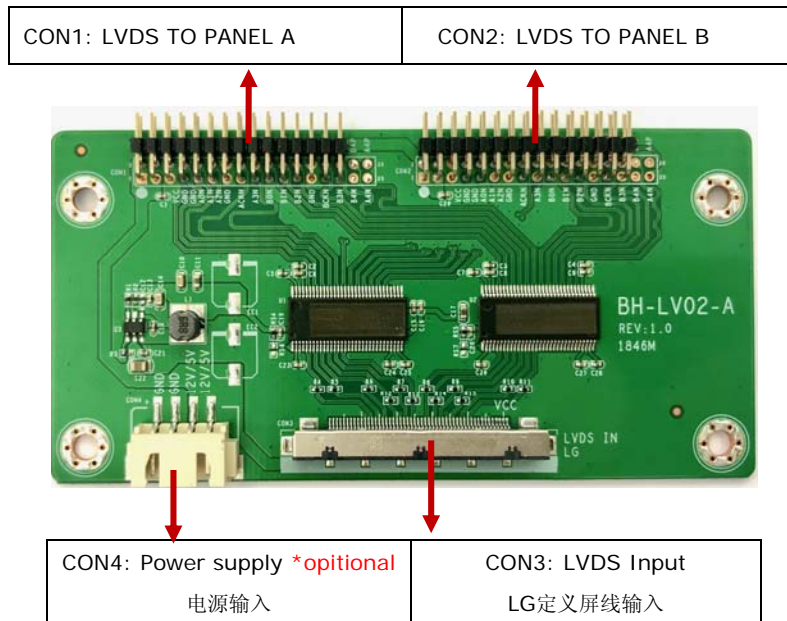
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1. GENERAL DESCRIPTION (概述)

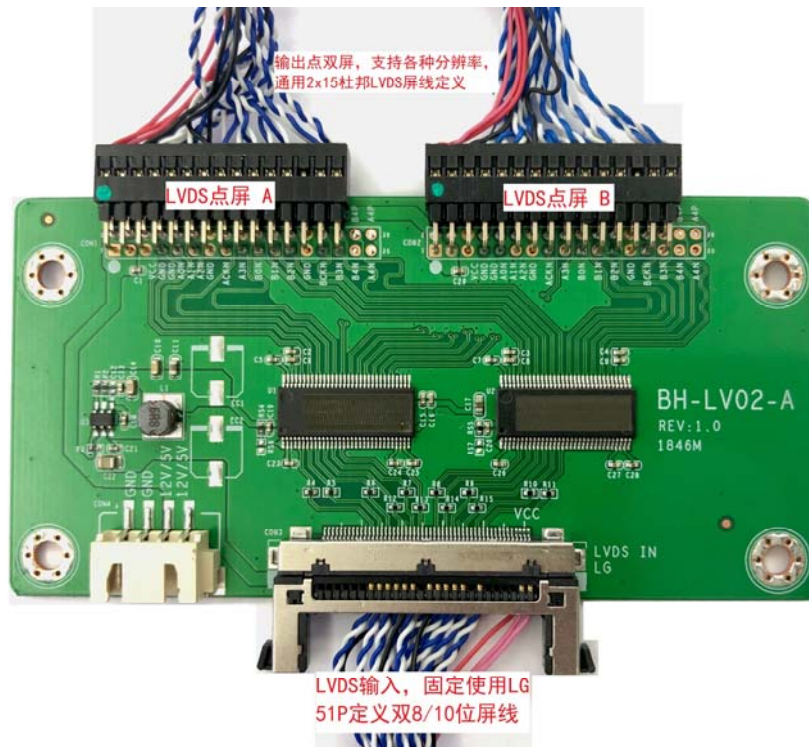
BH-LV02-A01 is a LVDS repeater and splitter PCBA board which can support various pixel rate up to WUXGA resolution. It can help one mainboard drive two LVDS panel.

BH-LV02-A01 是一款具有LVDS信号延长和复制功能的转接板，可以将输入信号一分二，实现单主板点双LVDS屏，广泛应用于超薄款双面显示需求。

2. FUNCTION LAYOUT (产品外观)



接线示意图:



3. FEATURES

COLOR DEPTH	8/10bit
LVDS FORMAT	JEIDA/VESA
POWER REQUIREMENT	12V or 5V
POWER CONSUMPTION	≤1W

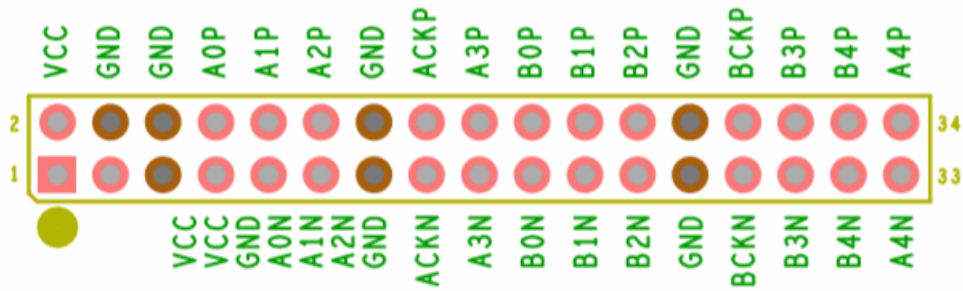
4. INTERFACE DEFINITION(接口定义)

◆ CON3 (51PIN/0.5): LVDS INPUT CONNECTOR(Same as LG)

- FI-RE51S-HF (manufactured by JAE)
- Mating Connector: FI-R51HL (JAE) or compatible

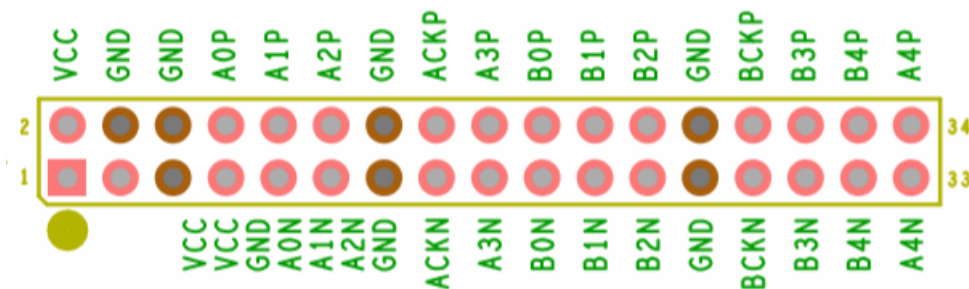
NO.	SYMBOL	DESCRIPTION	NO.	SYMBOL	DESCRIPTION
1	NC	No Connection	27	NC	No Connection
2	NC	No Connection	28	RxO0N	LVDS In ODD 0- Signal
3	NC	No Connection	29	RxO0P	LVDS In ODD 0+ Signal
4	NC	No Connection	30	RxO1N	LVDS In ODD 1- Signal
5	NC	No Connection	31	RxO1P	LVDS In ODD 1+ Signal
6	NC	No Connection	32	RxO2N	LVDS In ODD 2- Signal
7	NC	No Connection	33	RxO2P	LVDS In ODD 2+ Signal
8	NC	No Connection	34	GND	Ground
9	NC	No Connection	35	RxOCN	LVDS In ODD Clock- Signal
10	NC	No Connection	36	RxOCP	LVDS In ODD Clock+ Signal
11	GND	Ground	37	GND	Ground
12	RXE0N	LVDS In EVEN 0- Signal	38	RxO3N	LVDS In ODD 3- Signal
13	RXE0P	LVDS In EVEN 0+ Signal	39	RxO3P	LVDS In ODD 3+ Signal
14	RXE1N	LVDS In EVEN 1- Signal	40	NC	No Connection
15	RXE1P	LVDS In EVEN 1+ Signal	41	NC	No Connection
16	RXE2N	LVDS In EVEN 2- Signal	42	NC	No Connection
17	RXE2P	LVDS In EVEN 2+ Signal	43	NC	No Connection
18	GND	Ground	44	GND	Ground
19	RXECLKN	LVDS In EVEN Clock- Signal	45	GND	Ground
20	RXECLKP	LVDS In EVEN Clock+ Signal	46	GND	Ground
21	GND	Ground	47	NC	No Connection
22	RXE3N	LVDS In EVEN 3- Signal	48	VCC	+12V/5V Power Supply
23	RXE3P	LVDS In EVEN 3+ Signal	49	VCC	+12V/5V Power Supply
24	NC	No Connection	50	VCC	+12V/5V Power Supply
25	NC	No Connection	51	VCC	+12V/5V Power Supply
26	NC	No Connection	-	-	-

◆ CON1 (2x17PIN/2.0): LVDS OUTPUT CONNECTOR



NO.	SYMBOL	DESCRIPTION	NO.	SYMBOL	DESCRIPTION
1	VCC	+12V/5V for LCD	2	VCC	+12V/5V for LCD
3	VCC	+12V/5V for LCD	4	GND	Ground
5	GND	Ground	6	GND	Ground
7	TxE0N	LVDS Out EVEN 0- Signal	8	TxE0P	LVDS Out EVEN 0+ Signal
9	TxE1N	LVDS Out EVEN 1- Signal	10	TxE1P	LVDS Out EVEN 1+ Signal
11	TxE2N	LVDS Out EVEN 2- Signal	12	TxE2P	LVDS Out EVEN 2+ Signal
13	GND	Ground	14	GND	Ground
15	TXECKLN	LVDS Out EVEN Clock- Signal	16	TXECKLP	LVDS Out EVEN Clock+ Signal
17	TxE3N	LVDS Out EVEN 3- Signal	18	TxE3P	LVDS Out EVEN 3+ Signal
19	TxO0N	LVDS Out ODD 0- Signal	20	TxO0P	LVDS Out ODD 0+ Signal
21	TxO1N	LVDS Out ODD 1- Signal	22	TxO1P	LVDS Out ODD 1+ Signal
23	TxO2N	LVDS Out ODD 2- Signal	24	TxO2P	LVDS Out ODD 2+ Signal
25	GND	Ground	26	GND	Ground
27	TXOCN	LVDS Out ODD Clock- Signal	28	TXOCP	LVDS Out ODD Clock- Signal
29	TxO3N	LVDS Out ODD 3- Signal	30	TxO3P	LVDS Out ODD 3+ Signal
31	TxO4N	LVDS Out ODD 4- Signal	32	TxO4P	LVDS Out ODD 4+ Signal
33	TXE4N	LVDS Out EVEN 4- Signal	34	TXE4P	LVDS Out EVEN 4+ Signal

◆ CON2 (2x17PIN/2.0): LVDS OUTPUT CONNECTOR



NO.	SYMBOL	DESCRIPTION	NO.	SYMBOL	DESCRIPTION
1	VCC	+12V/5V for LCD	2	VCC	+12V/5V for LCD
3	VCC	+12V/5V for LCD	4	GND	Ground
5	GND	Ground	6	GND	Ground

7	TxE0N	LVDS Out EVEN 0- Signal	8	TxE0P	LVDS Out EVEN 0+ Signal
9	TxE1N	LVDS Out EVEN 1- Signal	10	TxE1P	LVDS Out EVEN 1+ Signal
11	TxE2N	LVDS Out EVEN 2- Signal	12	TxE2P	LVDS Out EVEN 2+ Signal
13	GND	Ground	14	GND	Ground
15	TXECLKN	LVDS Out EVEN Clock- Signal	16	TXECLKP	LVDS Out EVEN Clock+ Signal
17	TxE3N	LVDS Out EVEN 3- Signal	18	TxE3P	LVDS Out EVEN 3+ Signal
19	TxO0N	LVDS Out ODD 0- Signal	20	TxO0P	LVDS Out ODD 0+ Signal
21	TxO1N	LVDS Out ODD 1- Signal	22	TxO1P	LVDS Out ODD 1+ Signal
23	TxO2N	LVDS Out ODD 2- Signal	24	TxO2P	LVDS Out ODD 2+ Signal
25	GND	Ground	26	GND	Ground
27	TXOCP	LVDS Out ODD Clock- Signal	28	TXOCP	LVDS Out ODD Clock+ Signal
29	TxO3N	LVDS Out ODD 3- Signal	30	TxO3P	LVDS Out ODD 3+ Signal
31	TxO4N	LVDS Out ODD 4- Signal	32	TxO4P	LVDS Out ODD 4+ Signal
33	TxE4N	LVDS Out EVEN 4- Signal	34	TxE4P	LVDS Out EVEN 4+ Signal

◆ **CON4 (4PIN/2.54): POWER INPUT CONNECTOR**(*Note1 optional)

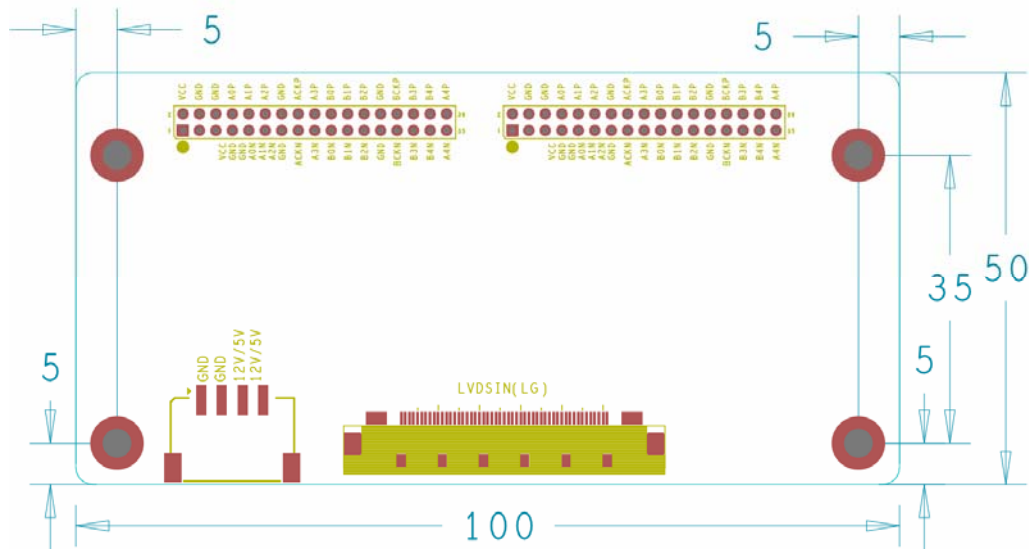
NO.	SYMBOL	DESCRIPTION
1	GND	Ground
2	GND	
3	VIN	+5V or 12V power supply
4	VIN	+5V or 12V power supply

Note1: 12V/5V power supply, optional.

根据屏的供电要求选择12V或5V单独供电；点双屏在主板LVDS线供电不足时，需接电源板单独供电！

5. PCB Dimension 尺寸图

The overall height of BH-LV02-A01 is 16 mm.



6. CONFIGURATION & GENERAL PRECAUTIONS

使用环境和注意事项

- Storage temperature: -10~60°C.
- 存储温度: -10~60°C。
- Operation temperature: 0~40°C.
- 工作温度: 0~40°C。
- Operating: 10% to 90% (Non-condensing, 无冷凝)
- 工作湿度: 10% ~ 90%
- Store: 5% to 95%
- 储存湿度: 5%~95%
- Operating: 10,000ft (max)
- 工作高度: 10,000ft (最大)
- Store: 20,000ft (max)
- 储存高度: 20,000ft (最大)
- Vibration (振动) 5-55Hz, 19.6m/s²(2G), 20minutes each along X, Y and Z axis.
- Protect the board from static electricity in case of damage to the IC.
- 请使板卡远离静电。
- Keep the board away from conductor when it is working.
- 请确保板卡工作时远离导体。
- Don't push or pull the connectors when the board is working.
- 板卡工作时请勿按压和扭曲。
- Don't press, distort or disassemble the board.
- 请勿拆解板卡。
- Clean the board with soft dry cloth when it's dirty.
- 如果板卡脏了, 请用干布擦拭。
- Don't wire in the board to power supply before panel is correctly connected.
- 正确接好驱屏线前请勿接通电源。

- Inner wires of the whole set should match reasonable, we suggest the LVDS twisted pair wire between the main board and panel must be tied up well and try to use shielding wire. If it's possible, try to put on the magnetic belt ring on the wire which near the board terminal, each connected wire try to not directly cross the PCB board, especially cross over from the main chips, avoid affecting the whole set EMC performance.
- 机内需合理布线，芯片上方不建议走线，LVDS屏线必须使用双绞线并建议使用屏蔽网，同时将地环锁死在PCB孔位上。

7. PACKING, SHIPPING & STORING (包装、运输、贮存)

7.1、Packing (包装)

Product name, part number, supplier's logo, QC stamp, Pb-free display and date must be printed on the package case.

包装箱上有产品名称、型号、厂家标识、厂家质量部门的检验合格证、制造日期等。

7.2、Shipping (运输)

This product can be transported through land, sea or air. Measures should be taken for water and sun proof. Also, it should be handled with care.

适应于车、船、飞机运输，运输中应遮篷、防晒、文明装卸。

7.3、Storing(贮存)

Please keep staying in the package case before using and keep away from hazardous gas, flammable or explosive substances and erosive chemical material. Avoid dramatic vibration or shock and strong magnetic field. The package cases should be racked 20cm above the ground and 50cm away from the wall, window, heat source or ventilation port. Generally, the storage term of this product is 2 years. All the products should be double checked after that time.

产品未使用时应存放在包装箱内，仓库内不允许有有害气体，易燃，易爆的产品及有腐蚀性的化学物品，并且无强烈的机械振动，冲击和强磁场作用，包装箱应垫离地至少20cm高，距离墙壁、热源、窗口或空气入口至少50cm，在本规定条件下的贮存期一般为2年，超过2年后应重新进行检验。